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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10087989	03/05/2002	438	438	2842	D VU

**APPLICANTS: Han Hongtao; Mathews Jay;

**CONTINUING DATA VERIFIED: Yes DV
THIS APPLICATION IS A CIP OF 09/983,278 10/23/2001
WHICH CLAIMS BENEFIT OF 60/273,321 03/06/2001

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** FOREIGN APPLICATIONS VERIFIED: None DV

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		DOC.072CIP
Verified and Acknowledged Examiners's initials		
TITLE : Thick wafer processing and resultant products		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-9)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
ISSUE FEE		Sheets Drwg.	Figs. Drwg.
Amount Due	Date Paid	Print Fig.	
Primary Examiner		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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